

KE-1151

Product Description

Shin-Etsu's KE-1151 is a single component, heat cure, phenyl-based polysiloxane potting gel that will cure to form a soft pliable elastomer to protect sensitive electronic components. KE-1151 provides superior vibration resistance and exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- Superior vibration resistance
- Excellent electrical insulation
- Single component
- Heat cure

Typical Applications

- Protecting sensitive electronic components

Typical Properties

Type	Potting Gel
Cure Type	Addition
One/Two Component	One
Cold Storage	Y
Color	Translucent
Density @ 23C (g/cm ³)	1.00
Viscosity (cps)	2500.00
Cure Conditions	30min @ 130C
Penetration (1/10mm)	90
Volume Resistivity (TΩ·m)	8
Dielectric Strength (kV/mm)	18
Dielectric Constant	3.0 @ 50Hz
Dielectric Dissipation Factor	5x10 ⁻⁴ @ 50Hz
Thermal Conductivity (W/m·K)	0.20
Usable Temperature Range (C)	-60 to +150

Note: Values are not for specification purposes.

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